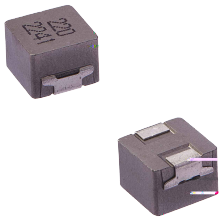
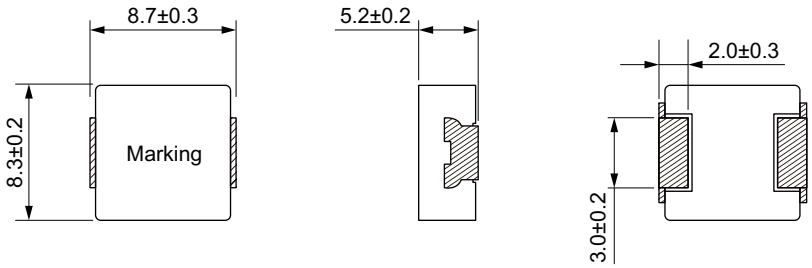
SMD Low Profile High Current Molded Inductor
Size 8054

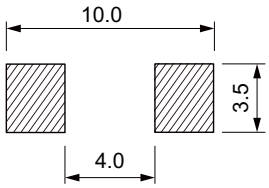


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## Dimensions: [mm]




## Land Pattern: [mm]

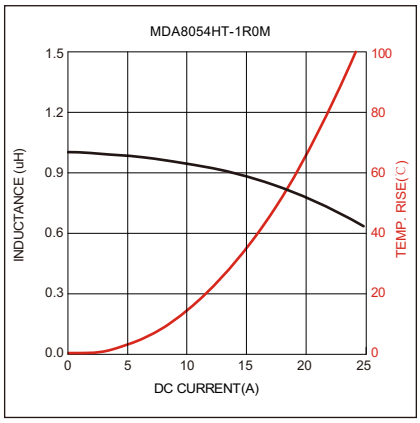


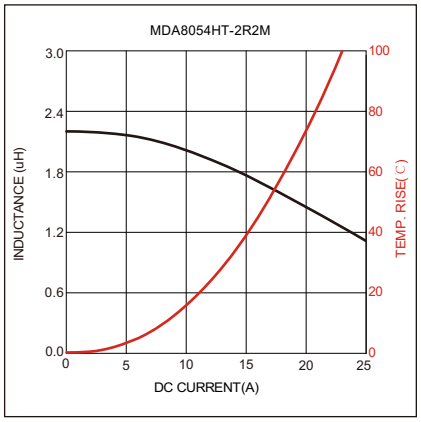

## Electrical Properties:

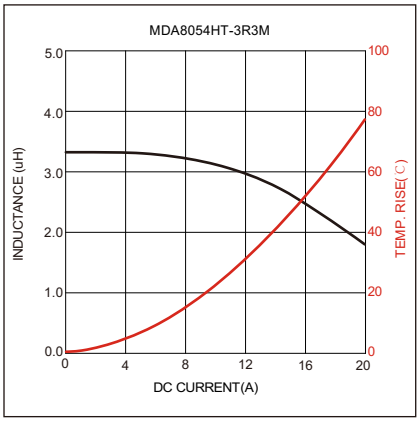
| Part No | Inductance @ 100KHz/1V (μH) | Tolerance | Temperature Rise Current Typ. (A) | Temperature Rise Current Max. (A) | Saturation Current Typ. (A) | Saturation Current Max. (A) | DC Resistance Typ. (mΩ) | DC Resistance Max. (mΩ) |
|---|---|---|---|---|---|---|---|---|
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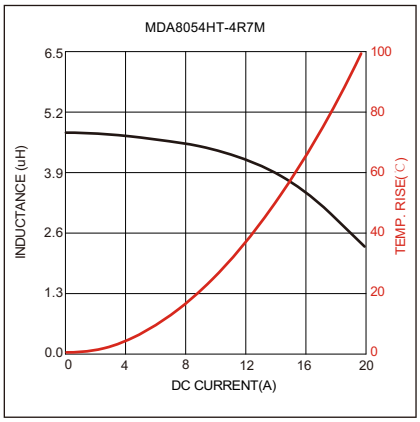
Saturation Current will cause L to drop approximately 35%
Temperature Rise Current: The actual value of DC current when the temperature rise is △T=40°C

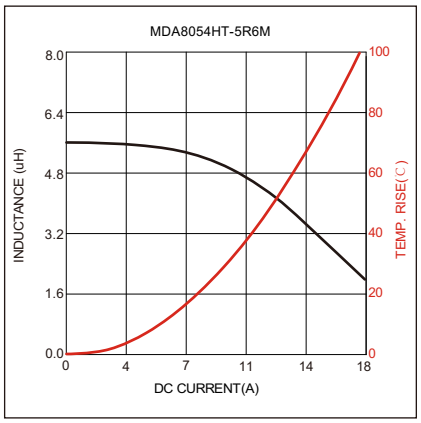
# Typical Electrical Characteristics:

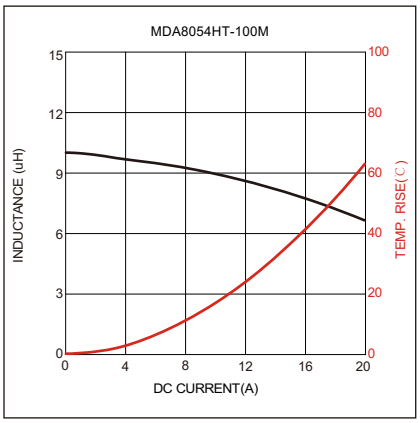


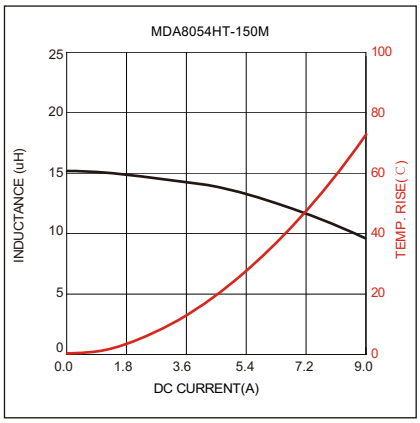



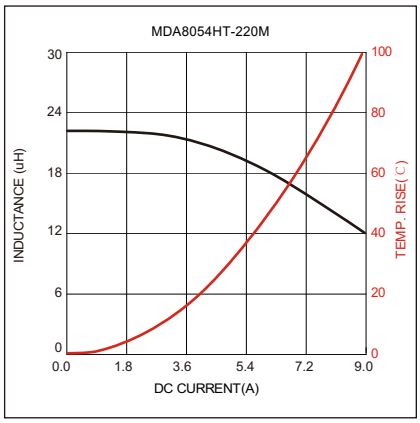



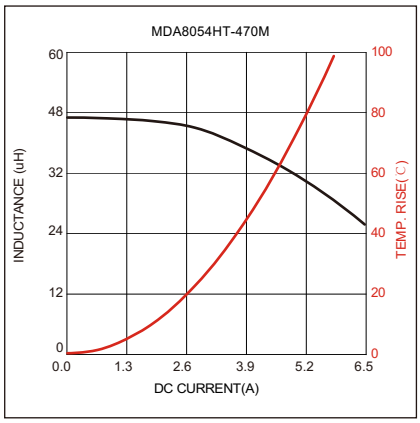



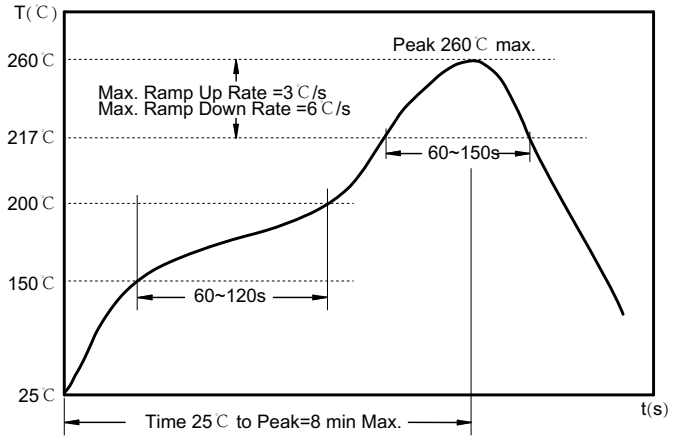



## Soldering Reflow:




Preheat condition: 150 ~200℃/ 60~120 sec.

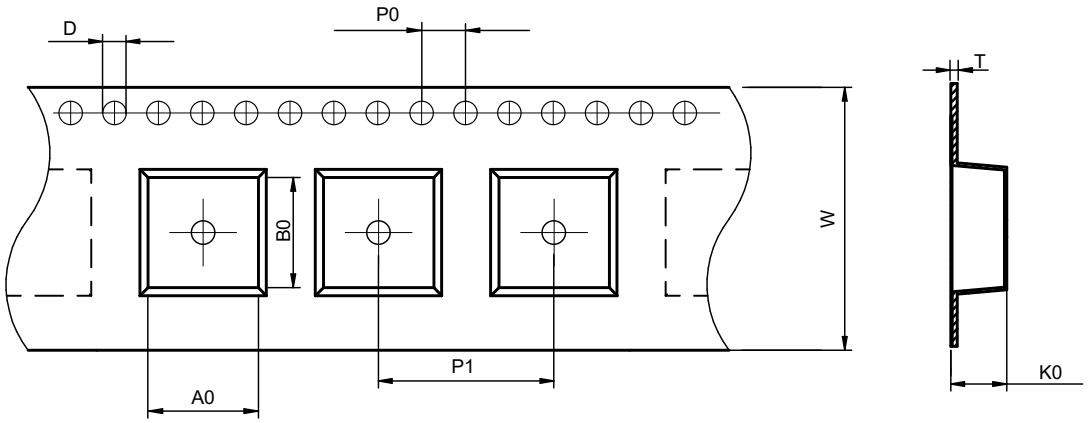
Allowed time above 217℃: 60~150 sec.

Max temperature: 260℃.

Allowed Reflow time: 2x max.

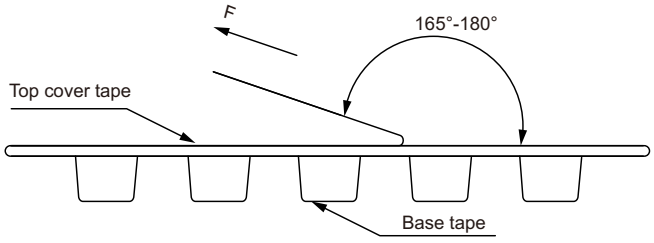
## Packaging Information:

### Tape Dimension:




| Series | A0 (mm) | B0 (mm) | D (mm) | P0 (mm) | P1 (mm) | W (mm) | K0 (mm) | T (mm) |
|---|---|---|---|---|---|---|---|---|
| MDA8054HT | 8.9±0.1 | 9.0±0.1 | 1.5±0.1 | 4.0±0.1 | 16.0±0.1 | 24.0±0.3 | 5.9±0.1 | 0.40±0.05 |

### Peel force of top cover tape:

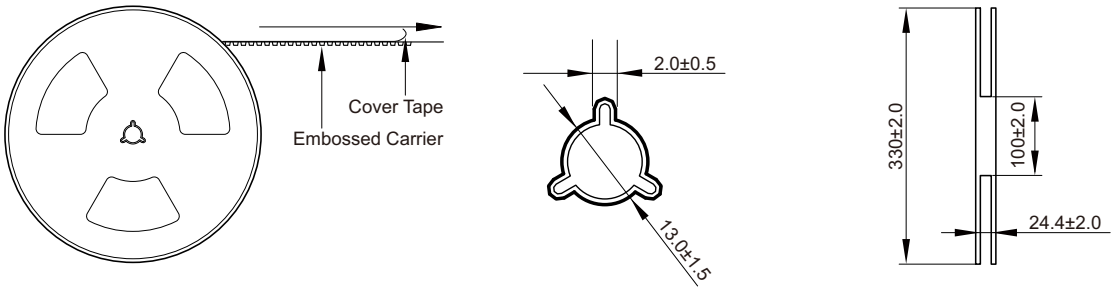



The peel force of top cover tape shall be between 0.1 to 1.27 N

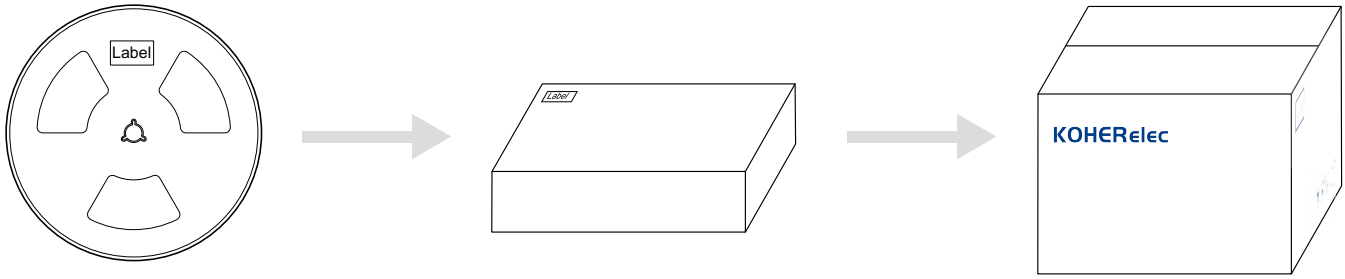
### Product Marking:

| Marking | Printing (Inductance+period) |
|---|---|

## Reel Dimension：[mm]




## Packaging Quantity:




500 Pcs/Reel

2 Reel /Inner box( 1000 Pcs)

3 Inner box/Carton box(3K Pcs)

# Cautions and Warnings:

## Storage Conditions：

- The storage period is within 12 months after the completion of production. Be sure to follow the storage conditions (temperature: -5 to 35°C, humidity: 75% RH Max).If the storage period elapses, the soldering of the terminal electrodes may deteriorate.The warranty period is one year.
- Product should not be exposed to environment with high temperature, high humidity, dust, corrosive gas and etc.
- Products should be handled with care to avoid damage or contamination from perspiration and skin oils.
- Please always handle products carefully to prevent any damage caused by dropping down or inappropriate removing.

## Operation Instructions:

- Self heating (temperature increase) occurs when the power is turned ON, so the tolerance should be sufficient for the set thermal design.
- Before soldering, be sure to preheat components.The preheating temperature should be set so that the temperature difference between the solder temperature and chip temperature does not exceed 150°C.
- Soldering corrections after mounting should be within the range of the conditions determined in the specifications.If overheated, a short circuit, performance deterioration, or lifespan shortening may occur.
- Generally, Koher might not be familiar with either customer's specific application or actual requests as customer does.As a result customer shall be responsible for checking and confirming whether Koher product with the performance described in the product specification is suitable for using in customer's particular application or not.